

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:	)	
	)	
Chen, et al.	)	Confirmation No.: 9818
	)	
Serial No.: 10/810,965	)	Examiner: Trinh, Hoa B.
	)	
Filed: March 26, 2004	)	Group Art Unit: 2814
	)	
For: Novel Method to Improve Bump Reliability for	)	TKHR Docket: 252016-2530
Flip Chip Device	)	Top-Team: 0503-A30731US

**RESPONSE TO FINAL OFFICE ACTION**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

The FINAL Office Action mailed April 24, 2005 has been carefully considered. In response thereto, please consider the following remarks.